

### PROTECTION PRODUCTS

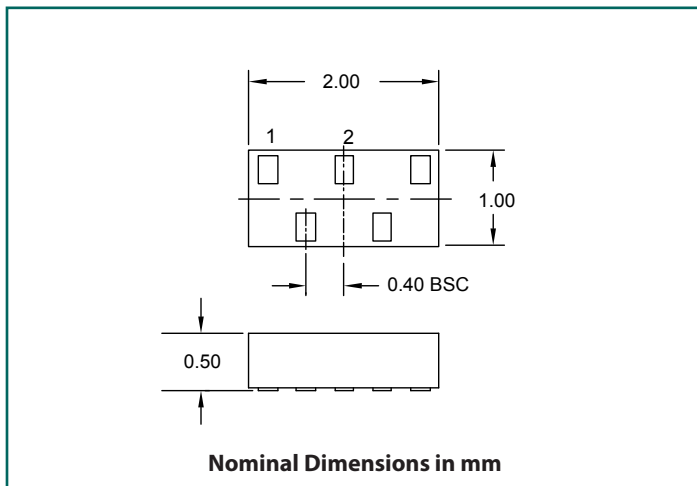
#### Description

RClamp®0564P is an ultra low capacitance ESD protection device specifically designed to protect high-speed differential lines. It offers desirable characteristics for board level protection including fast response time, low operating and clamping voltage, and no device degradation.

RClamp0564P features extremely good ESD protection characteristics highlighted by low peak ESD clamping voltage, and high ESD withstand voltage (+/-10kV contact per IEC 61000-4-2). RClamp0564P is designed to minimize both the ESD peak clamping and the TLP clamping. Package inductance is reduced at each pin resulting in lower peak ESD clamping voltage. RClamp0564P has a typical capacitance of 0.17pF allowing it to be used in high bandwidth applications such as HDMI 2.0 4K/2K, Thunderbolt, and USB 3.1. Each device will protect four high-speed data lines operating up to 5 volts.

RClamp0564P is in a 5-pin SGP2010N5 package measuring 2.0 x 1.0mm with a nominal height of 0.50mm. The leads have a nominal pin-to-pin pitch of 0.40mm. Flow-through package design simplifies PCB layout and maintains signal integrity on high-speed lines.

#### Nominal Dimensions



#### Features

- High ESD Withstand Voltage
  - ♦ IEC 61000-4-2 (ESD) 10kV (contact)
- Ultra-Low Capacitance: 0.17pF Typical
- Very Small PCB Area
- Protects Four High-Speed Data Lines
- Working Voltage: 5V
- Low Dynamic Resistance: 0.65 Ohms
- Large Operating Bandwidth: 12GHz
- Solid-State Silicon-Avalanche Technology

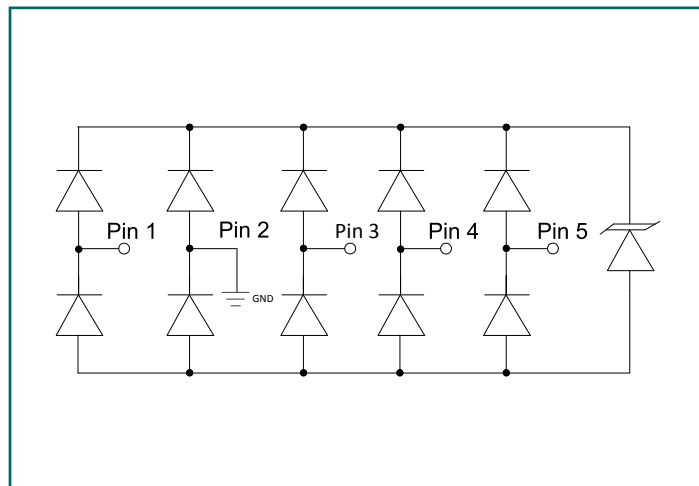
#### Mechanical Characteristics

- SGP2010N5 Package
- Pb-Free, Halogen Free, RoHS/WEEE Compliant
- Nominal Dimensions: 2.0 x 1.0 x 0.50 mm
- Lead Pitch: 0.40mm
- Lead Finish: NiPdAu
- Marking : Marking Code
- Packaging : Tape and Reel

#### Applications

- HDMI 1.4, HDMI1.4b and HDMI 2.0
- DisplayPort
- USB 3.0 and USB 3.1
- USB Type-C
- Thunderbolt
- MIPI / MDDI

#### Schematic



## Absolute Maximum Ratings

Rating	Symbol	Value	Units
Peak Pulse Current (tp = 8/20μs)	I <sub>PP</sub>	3	A
ESD per IEC 61000-4-2 (Contact) <sup>(1)</sup> ESD per IEC 61000-4-2 (Air) <sup>(2)</sup>	V <sub>ESD</sub>	±10 ±15	kV
Operating Temperature	T <sub>J</sub>	-40 to +85	°C
Storage Temperature	T <sub>STG</sub>	-55 to +150	°C

## Electrical Characteristics (T=25°C unless otherwise specified)

Parameter	Symbol	Conditions	Min.	Typ.	Max.	Units
Reverse Stand-Off Voltage	V <sub>RWM</sub>	-40°C to 85°C			5	V
Reverse Breakdown Voltage	V <sub>BR</sub>	I <sub>t</sub> = 10mA -40°C to 85°C	6.5	9.5	10.5	V
Holding Current	I <sub>H</sub>			100		mA
Reverse Leakage Current	I <sub>R</sub>	V <sub>RWM</sub> = 5V	T = 25°C	1	50	nA
			T = 85°C	10	150	nA
Clamping Voltage <sup>3</sup>	V <sub>C</sub>	I <sub>pp</sub> = 3A, tp = 8/20μs		4		V
ESD Clamping Voltage <sup>4</sup>	V <sub>C</sub>	I <sub>pp</sub> = 4A, tp = 0.2/100ns (TLP)		5.5		V
ESD Clamping Voltage <sup>4</sup>	V <sub>C</sub>	I <sub>pp</sub> = 16A, tp = 0.2/100ns (TLP)		13.5		V
Dynamic Resistance <sup>4,5</sup>	R <sub>DYN</sub>	tp = 0.2/100ns (TLP)		0.65		Ohms
Junction Capacitance	C <sub>J</sub>	V <sub>R</sub> = 0V, f = 1MHz T = 25°C		0.17	0.20	pF
Cutoff Frequency	F <sub>C</sub>	-3dB		12		GHz

### Notes:

(1) Measured with a 40dB attenuator, 50 Ohm scope input impedance, 2GHz bandwidth. ESD gun return path connected to Ground Reference Plane (GRP)

(2) In-System ESD withstand voltage

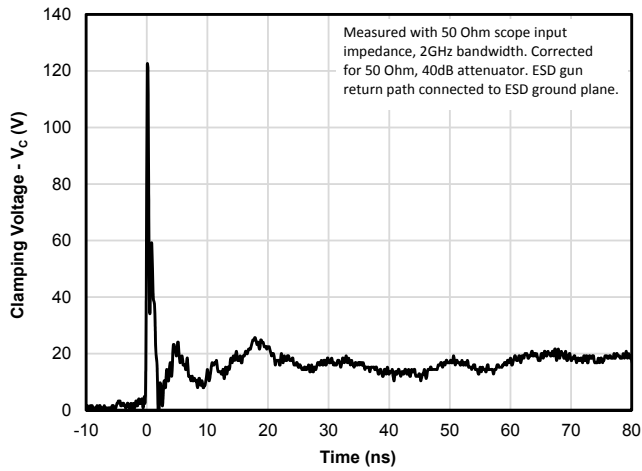
(3) Measured using a 1.2/50us voltage, 8/20us current combination waveform. Clamping is defined as the peak voltage across the device after the device snaps back to a conducting state.

(4) Transmission Line Pulse Test (TLP) Settings: tp = 100ns, tr = 0.2ns, I<sub>TLP</sub> and V<sub>TLP</sub> averaging window: t<sub>1</sub> = 70ns to t<sub>2</sub> = 90ns.

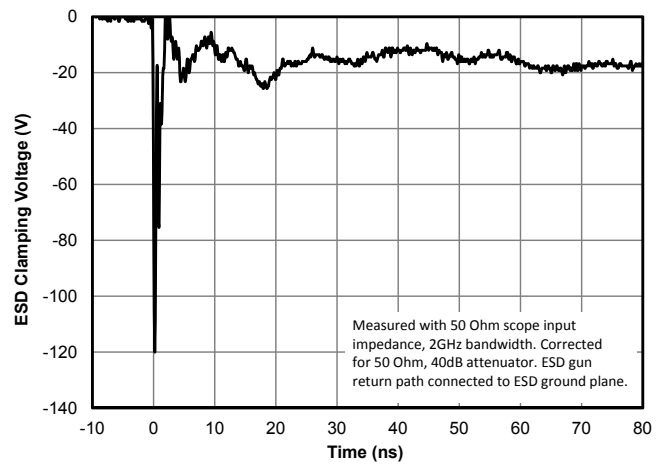
(5) Dynamic resistance calculated from I<sub>TLP</sub> = 4A to I<sub>TLP</sub> = 16A

# Typical Characteristics

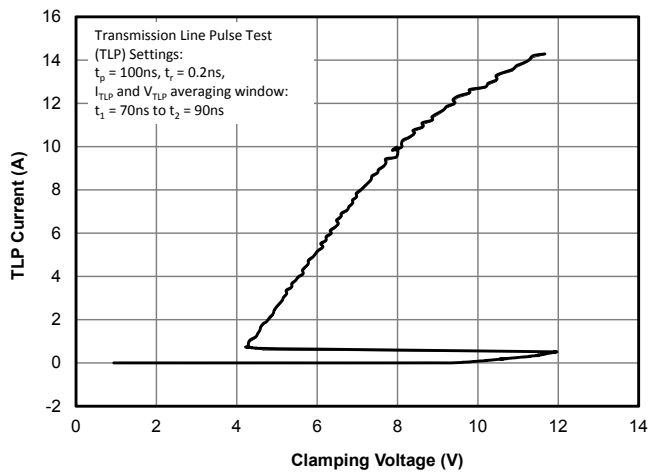
## ESD Clamping (+8kV Contact per IEC 61000-4-2)



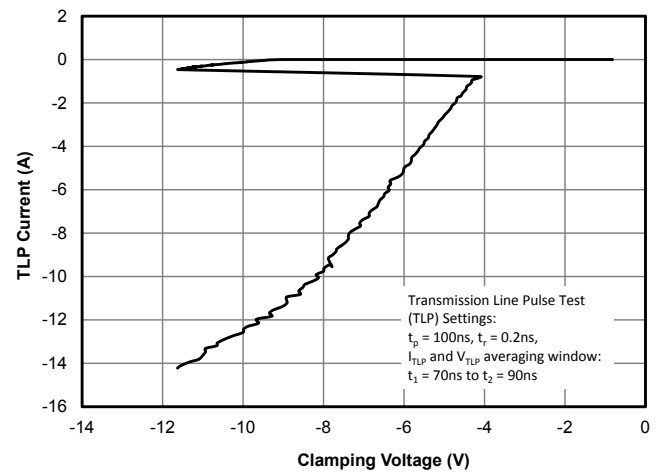
## ESD Clamping (-8kV Contact per IEC 61000-4-2)



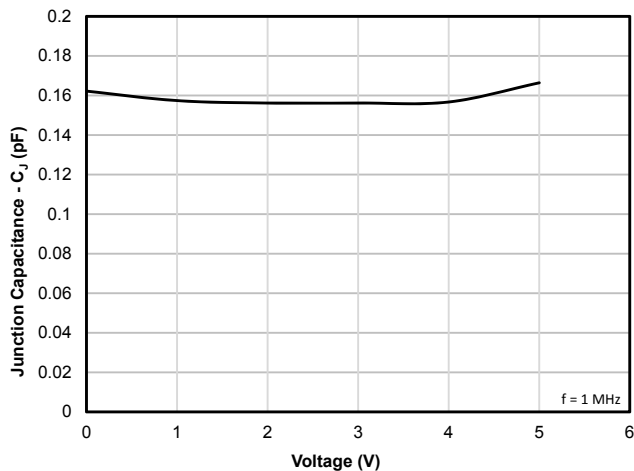
## TLP IV Curve - Positive Pulse



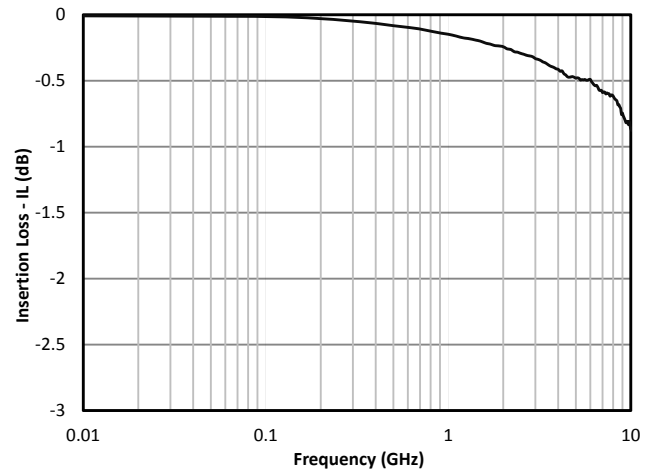
## TLP IV Curve - Negative Pulse



## Capacitance vs. Reverse Voltage



## Insertion Loss (S21)



# Application Information

## HDMI 2.0 Interface Protection

HDMI 2.0 chips are constantly exposed to external ESD and cable discharge threats. Adding external ESD protection is critical but can be challenging. Both electrical and mechanical requirements must be considered. HDMI 2.0 provides the necessary bandwidth to support the higher resolution and frame rates of Ultra HD. This is accomplished by increasing the data rate on each data lane from 3.4 Gbps to 6 Gbps, which means the protection device must present an extremely low capacitance to preserve signal integrity. The external protection device should also have good ESD protection properties including low ESD peak clamping voltage and low dynamic resistance. Mechanically, the package design should allow the traces to easily flow through the package. This is important since differential pair trace lengths should be matched to avoid signal skew.

## Protection Solutions

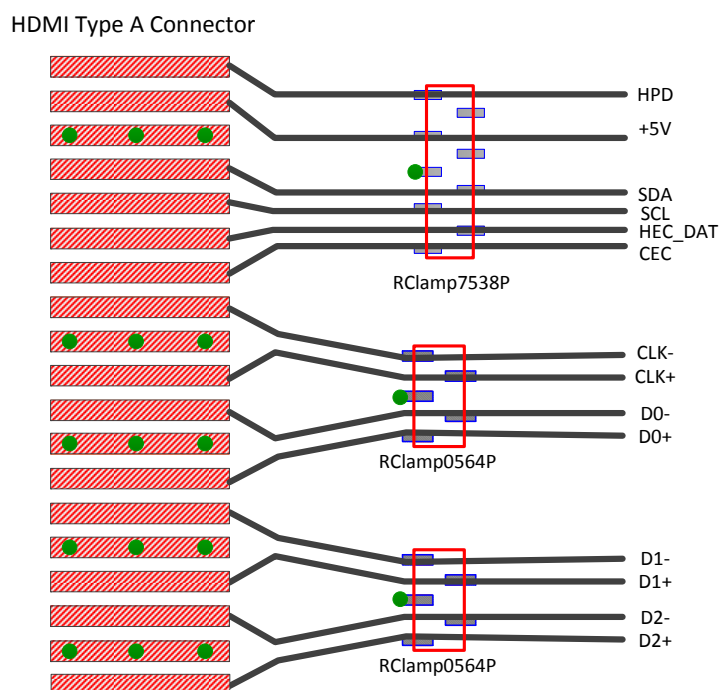
RClamp0564P has been specifically designed to protect high-speed interfaces. It has a typical capacitance of 0.17pF and a flow through package design.

A typical HDMI 2.0 protection solution is shown below. RClamp0564P is used to protect two high-speed differential data pairs. Line pairs are routed through pins 1, 5 and pins 3, 4. Ground connection is made at pin 2. RClamp0564P has little affect on a 5.94Gb/s signal with an HDMI 2.0 eye mask as shown in the eye diagrams below. Two RClamp0564P are required to protect all four clock and data differential pairs. The remaining six lines can also be protected using RClamp0564P. However, since they are not as sensitive to capacitive loading as the TMDS lines, a device such as RClamp7538P may be used as shown.

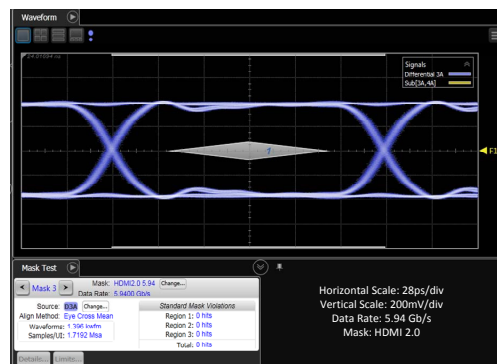
## Device Placement

Placement of the protection component is a critical element for effective ESD suppression. TVS diodes should be placed as close to the connector as possible to reduce transient coupling to nearby traces. Ground connections should be made directly to the ground plane using micro-vias. This reduces parasitic inductance in the ground path and minimizes the clamping voltage seen by the protected device.

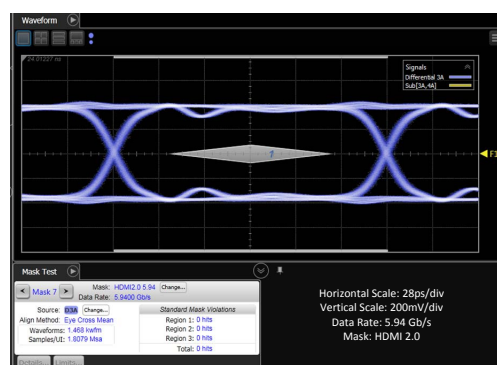
### HDMI 2.0 Protection Example



### 5.94Gb/s Eye Diagram with RClamp0564P



### 5.94Gb/s Eye Diagram without RClamp0564P



# Application Information

## DisplayPort Interface Protection

DisplayPort chips are constantly exposed to external ESD and cable discharge threats. Adding external ESD protection is critical but can be challenging. Both electrical and mechanical requirements must be considered. DisplayPort version 1.4 can use the HBR3 transmission mode (32.4 Gbits/s) provides the necessary bandwidth to support the higher resolution and frame rates of Ultra HD. This is accomplished by increasing the data rate on each data lane from 5.4 Gbps to 8.1 Gbps, which means the protection device must present an extremely low capacitance to preserve signal integrity. The external protection device should also have good ESD protection properties including low ESD peak clamping voltage and low dynamic resistance. Mechanically, the package design should allow the traces to easily flow through the package. This is important since differential pair trace lengths should be matched to avoid signal skew.

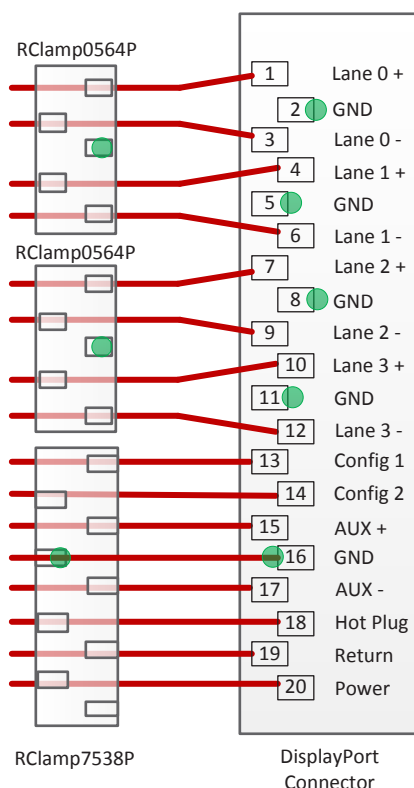
## Protection Solutions

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## Device Placement

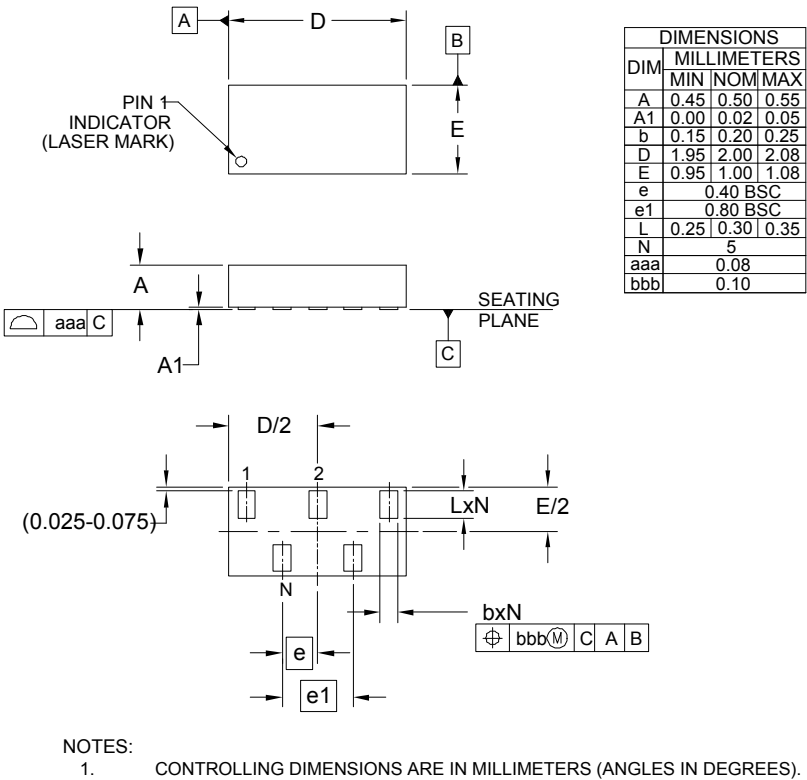
Placement of the protection component is a critical element for effective ESD suppression. TVS diodes should be placed as close to the connector as possible to reduce transient coupling to nearby traces. Ground connections should be made directly to the ground plane using micro-vias. This reduces parasitic inductance in the ground path and minimizes the clamping voltage seen by the protected device.

DisplayPort Protection Example

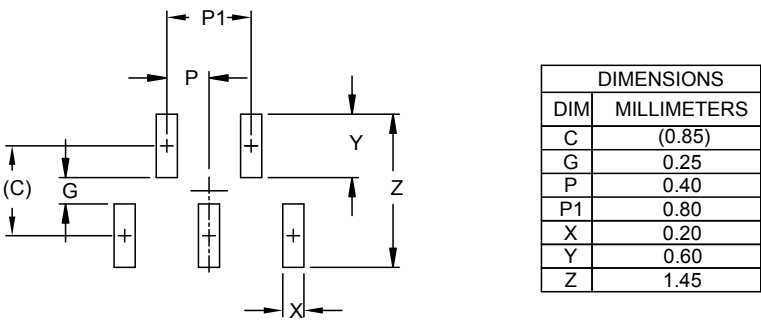




# Outline Drawing - SGP2010N5

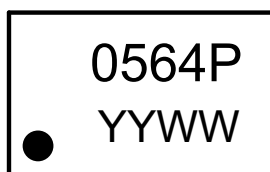


# Land Pattern - SGP2010N5



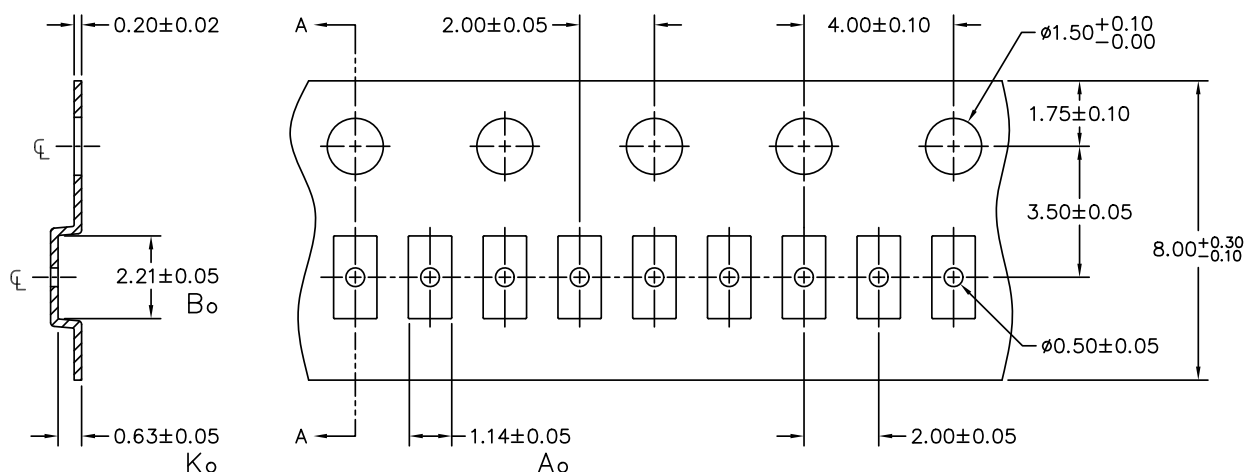
- NOTES:**
1. CONTROLLING DIMENSIONS ARE IN MILLIMETERS (ANGLES IN DEGREES).
  2. THIS LAND PATTERN IS FOR REFERENCE PURPOSES ONLY.  
CONSULT YOUR MANUFACTURING GROUP TO ENSURE YOUR COMPANY'S MANUFACTURING GUIDELINES ARE MET.

## Marking Code



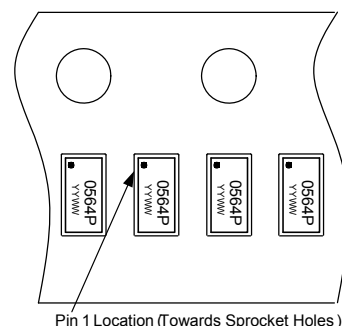
Notes: YYWW = Alphanumeric Date Code

## Tape and Reel Specification



SECTION A-A

NOTE: ALL DIMENSIONS IN MILLIMETERS UNLESS OTHERWISE SPECIFIED.



## Ordering Information

Part Number	Qty per Reel	Reel Size
RClamp0564P.TNT	10000	7 Inch
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